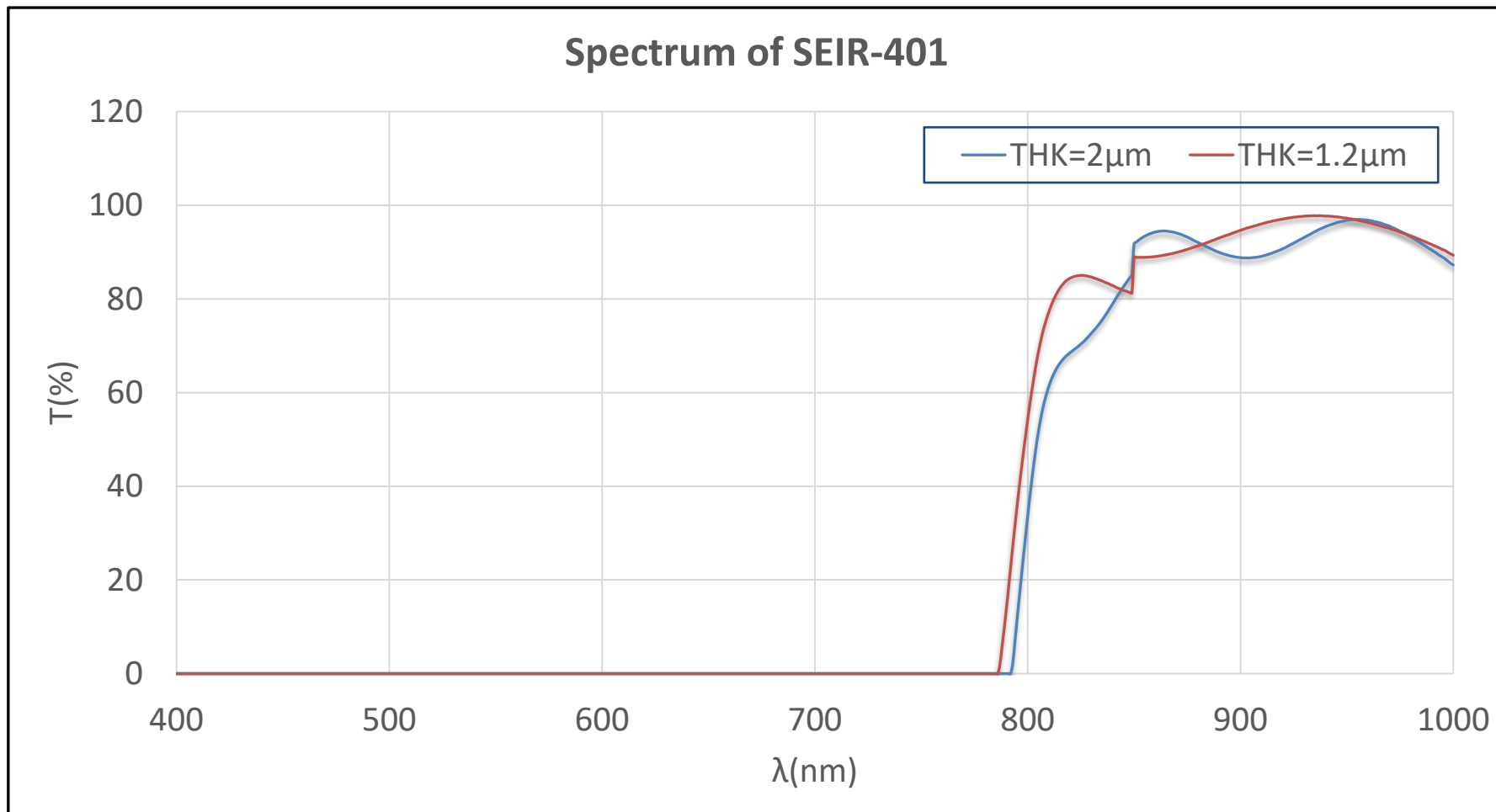


IR Pass Black Resist SEIR-401

IR-P BK	Viscosity (cps)	Resist Solid Content (%)	BT (sec)	Dev. time (sec)	THK (μm)	OD	CD (μm)	Adhesion (μm)
401	6.5	20	50	70	2.03	2.75	7.41	10
			35	55	1.22	1.69	4.81	6

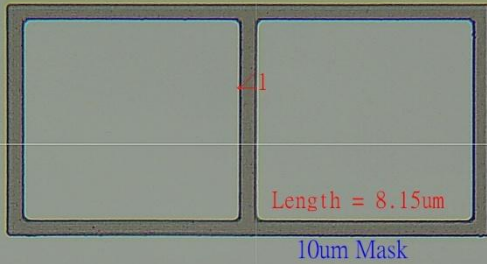
Process Parameter	
THK	Control at 1.4~2.2 μm before Post-bake
Pre-bake	100°C*2.5min, directly
Power	80mJ/ cm^2 & 30 μm @18mW
Dev.	55~70 sec in 1:99 KOH Type DVR / 0.15MPa & 25 °C
Rinse	20sec/ 0.15MPa & 25 °C
HPMJ	10sec/ 0.4MPa & 25 °C
Post-bake	200 °C*30min clean oven

Spectrum of SEIR-401



THK=2 & 1.2 μ m, Exp. Dose=80mJ/cm², Gap=30 μ m, Dev.=70s, Post-bake=200 $^{\circ}$ C *30min

Before Oven (THK=2 μm)



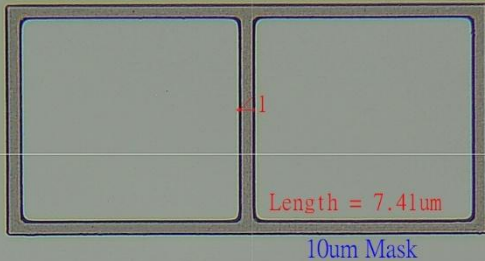
20X - 0.00037037 mm/pixel

Before Oven (THK=1.2 μm)



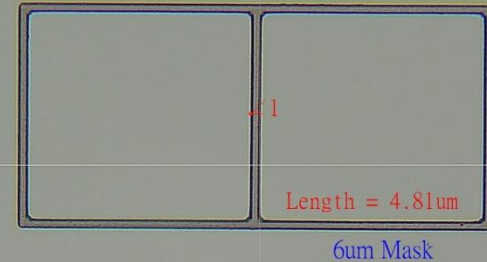
20X - 0.00037037 mm/pixel

After Oven (THK=2 μm)



20X - 0.00037037 mm/pixel

After Oven (THK=1.2 μm)

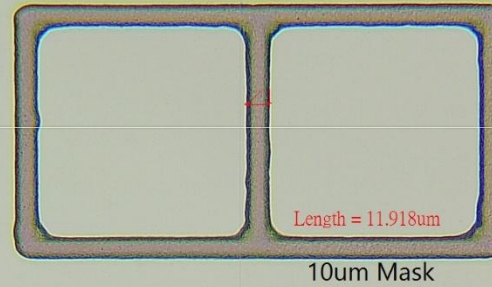


20X - 0.00037037 mm/pixel

THK=2 & 1.2 μm , Exp. Dose=80mJ/cm², Gap=30 μm , Dev.=70s, Post-bake=200°C *30min

SEIR-401 OM ~ 9 μ m Pattern

Before Oven(401)



20X - 0.00041096 mm/pixel

After Oven(401)



20X - 0.00041096 mm/pixel

THK=1.8 μ m, Exp. Dose=80mJ/cm², Gap=150 μ m, Dev.=70s, Postbake=230 $^{\circ}$ C *30min

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